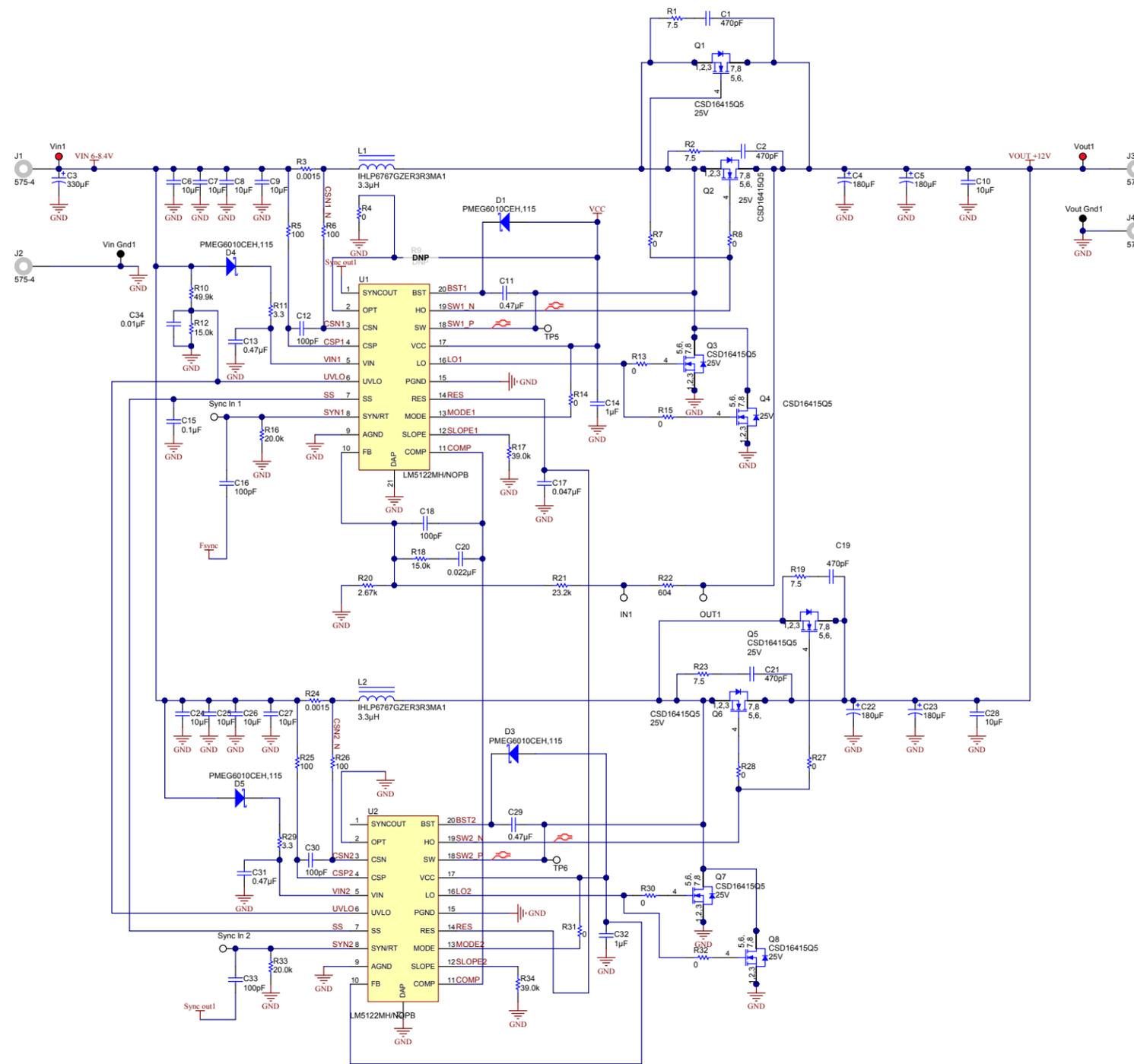


PMP10502 is build on PCB PMP7850 RevB

Input Voltage = 6Vin to 8.4Vin

12Vout @ 17A Continuous (34A Peak)



DNP
FID1

DNP
FID2

DNP
FID3

PCB: PMP7850 RevB
PMP7850 RevB

PCB
LOGO
Texas Instruments

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Designed for: Public Release		Mod. Date: 4/14/2015	
Project Title: LM5122 Sync Boost		Sheet Title:	
Number: PMP10502	Rev: 1	Assembly Variant: 001	Sheet 2 of 2
SVN Rev: Version control disabled	Drawn By: Engineer: Hrag Kasparian	File: PMP10502_Hardware_ANSI-B_SchDoc	Size: C
Contact: http://www.ti.com/support		http://www.ti.com	



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